

### L1404ZL-VB Datasheet

# N-Channel 40 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a, c</sup>	Q <sub>g</sub> (Typ.)		
40	0.0017 at V <sub>GS</sub> = 10 V	150	120 nC		
40	0.0025 at V <sub>GS</sub> = 4.5 V	135	120110		

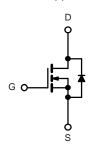
#### **FEATURES**

- Trench Power MOSFET
- 100 %  $R_g$  and UIS Tested



#### **APPLICATIONS**

- · Synchronous Rectification
- Power Supplies



N-Channel MOSFET

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Top View

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	40	V	
Gate-Source Voltage		V <sub>GS</sub>	± 25		
	T <sub>C</sub> = 25 °C		150 <sup>a, c</sup>	A	
Continuous Drain Current /T 475 °C)	T <sub>C</sub> = 70 °C	,	120 <sup>c</sup>		
Continuous Drain Current (T <sub>J</sub> = 175 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	29 <sup>b</sup>		
	T <sub>A</sub> = 70 °C		23 <sup>b</sup>		
Pulsed Drain Current		I <sub>DM</sub>	380		
Avalanche Current Pulse		I <sub>AS</sub>	80		
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	320	mJ	
Continuous Courses Brain Binds Coursest	T <sub>C</sub> = 25 °C	1	110 <sup>a, c</sup>	А	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	2.6 <sup>b</sup>		
	T <sub>C</sub> = 25 °C		312 <sup>a</sup>		
Manianum Danian Dinain atian	T <sub>C</sub> = 70 °C	В	200	w	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	3.13 <sup>b</sup>		
	T <sub>A</sub> = 70 °C		2.0 <sup>b</sup>		
Operating Junction and Storage Temperature Ra	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>b</sup> Steady State		R <sub>thJA</sub>	32	40	°C/W		
Maximum Junction-to-Case	Steady State	R <sub>thJC</sub>	0.33	0.4	C/VV		

#### Notes:

- a. Based on  $T_C$  = 25 °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. Calculated based on maximum junction temperature. Package limitation current is 110  $\,\mathrm{A.}$



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V, } I_D = 250  \mu\text{A}$	45			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = 250 μA		41		m\//°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	1 <sub>D</sub> = 230 μΛ		- 8		mV/°(	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.2		2.5	V	
Gate-Source Leakage	$I_{GSS}$	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zoro Coto Voltago Drain Current	lana	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10	μA	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α	
David Course Co. Otata Basista and	D	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A		0.0017			
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$		0.0025		Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 15 \text{ V}, I_{D} = 30 \text{ A}$		180		S	
Dynamic <sup>b</sup>	•						
Input Capacitance	C <sub>iss</sub>			9000			
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		650		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			450			
Total Gate Charge	$Q_{g}$			120	180	nC	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		30			
Gate-Drain Charge	Q <sub>gd</sub>			16			
Gate Resistance	$R_{g}$	f = 1 MHz		0.85	1.3	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			20	30		
Rise Time	t <sub>r</sub>	$V_{DD}$ = 20 V, $R_L$ = 1.0 $\Omega$		11	17		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 20 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		77	115		
Fall Time	t <sub>f</sub>			10	15		
Turn-On Delay Time	t <sub>d(on)</sub>			102	155	ns	
Rise Time	t <sub>r</sub>	$V_{DD}$ = 20 V, $R_L$ = 1.0 $\Omega$		62	95		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 20 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		180	270		
Fall Time	t <sub>f</sub>			60	90	1	
<b>Drain-Source Body Diode Characteristic</b>	s						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			110	^	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				200	Α	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 20 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			50	75	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	L = 20 A di/dt = 100 A/v = T = 05 °C		70	105	nC	
Reverse Recovery Fall Time	ta	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		30			
Reverse Recovery Rise Time t <sub>b</sub>				20		ns	

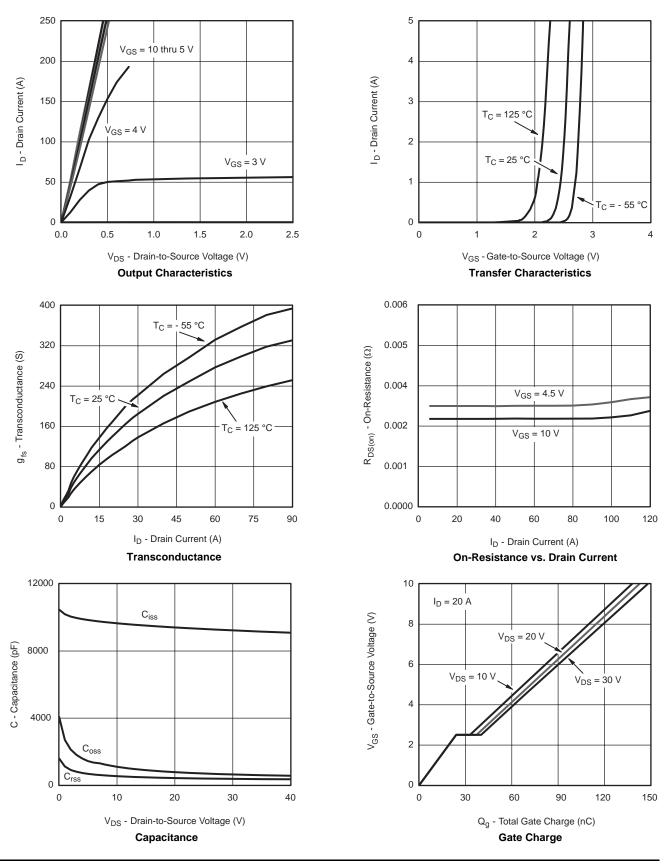
#### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

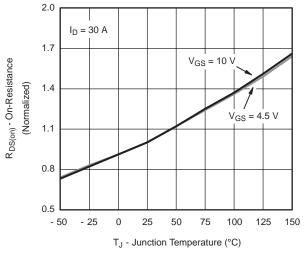


#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

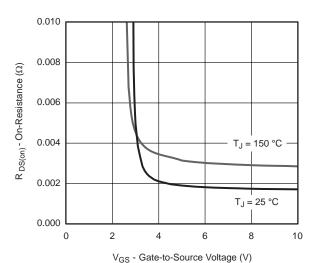




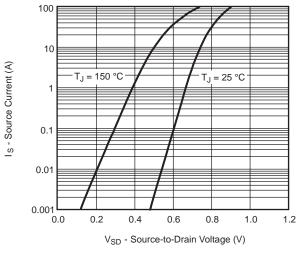
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#### On-Resistance vs. Junction Temperature



On-Resistance vs. Gate-to-Source Voltage



#### Forward Diode Voltage vs. Temperature



Threshold Voltage

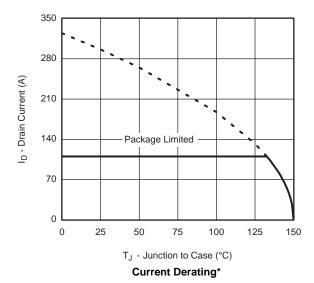


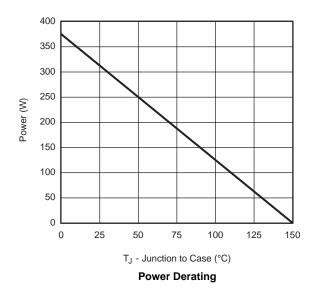
 $^*$   $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

Safe Operating Area, Junction-to-Ambient

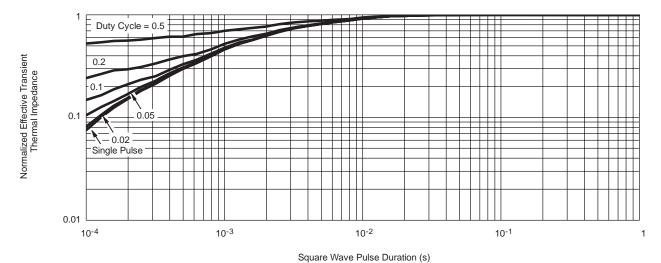


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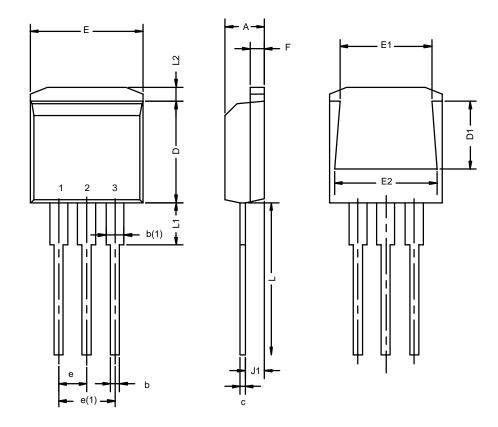
\* The power dissipation  $P_D$  is based on  $T_{J(max)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



Normalized Thermal Transient Impedance, Junction-to-Case



#### TO-262: 3-LEAD



	MILLIMETERS*		INC	HES	
Dim	Min	Max	Min	Max	
Α	4.32	4.70	0.170	0.185	
b	0.64	1.00	0.025	0.039	
b(1)	1.14	1.40	0.045	0.055	
С	0.36	0.50	0.014	0.020	
D	8.64	9.65	0.340	0.380	
D1	5.59	6.10	0.220	0.240	
е	2.41	2.67	0.095	0.105	
e(1)	4.95	5.33	0.195	0.210	
Е	10.03	10.41	0.395	0.410	
E1	7.87	8.64	0.310	0.340	
E2	9.02	9.53	0.355	0.375	
F	1.14	1.40	0.045	0.055	
J1	2.41	2.79	0.095	0.110	
L	13.08	14.22	0.515	0.560	
L1	-	3.81	-	0.150	
L2	1.02	1.40	0.040	0.055	
ECN: T-02234—Rev. C, 14-Oct-02 DWG: 5855					

<sup>\*</sup>Use millimeters as the primary measurement



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